Surface Mount Schottky Power Rectifier

SMB Power Surface Mount Package

These devices employ the Schottky Barrier principle in a metal-to-silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes.

Features

- Compact Package with J-Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guard-Ring for Overvoltage Protection
- Low Forward Voltage Drop
- Pb-Free Package is Available

Mechanical Characteristics

- Case: Molded Epoxy
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 95 mg (Approximately)
- Cathode Polarity Band
- Maximum Temperature of 260°C/10 Seconds for Soldering
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	40	V
Average Rectified Forward Current (At Rated V _R , T _C = 100°C)	I _O	2.0	Α
Peak Repetitive Forward Current (At Rated V _R , Square Wave, 20 kHz, T _C = 105°C)	I _{FRM}	4.0	Α
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	25	Α
Storage/Operating Case Temperature	T _{stg} , T _C	-55 to +150	°C
Operating Junction Temperature	TJ	-55 to +150	°C
Voltage Rate of Change (Rated V _R , T _J = 25°C)	dv/dt	10,000	V/μs

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



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SCHOTTKY BARRIER RECTIFIER 2.0 AMPERES, 40 VOLTS



SMB CASE 403A PLASTIC

MARKING DIAGRAM



2BL4 = Specific Device Code A = Assembly Location

Y = Year WW = Work

WW = Work Week ■ Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
MBRS240LT3	SMB	2500/Tape & Reel
MBRS240LT3G	SMB (Pb-Free)	2500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

1

THERMAL CHARACTERISTICS

18 78	°C/W
	18 78

ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage (Note 2)		V _F	T _J = 25°C	T _J = 125°C	V
see Figure 2	$(I_F = 2.0 \text{ A})$ $(I_F = 4.0 \text{ A})$		0.43 0.54	0.375 0.55	
Maximum Instantaneous Reverse Current (Note 2)		I _R	T _J = 25°C	T _J = 100°C	mA
see Figure 4	(V _R = 40 V) (V _R = 20 V)		2.0 0.5	60 40	

- 1. Mounted with minimum recommended pad size, PC Board FR4.
- 2. Pulse Test: Pulse Width ≤ 250 μs, Duty Cycle ≤ 2.0%.
- 3. 1 inch square pad size (1 x 0.5 inch for each lead) on FR4 board.

TYPICAL CHARACTERISTICS

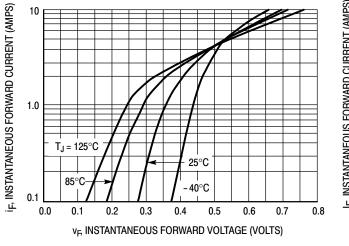


Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage

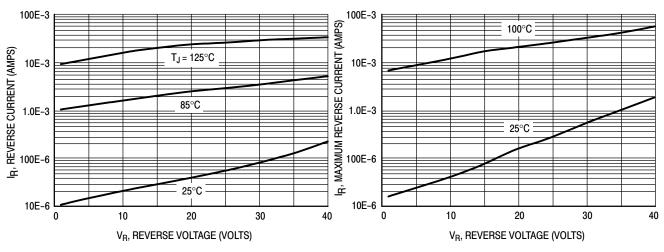
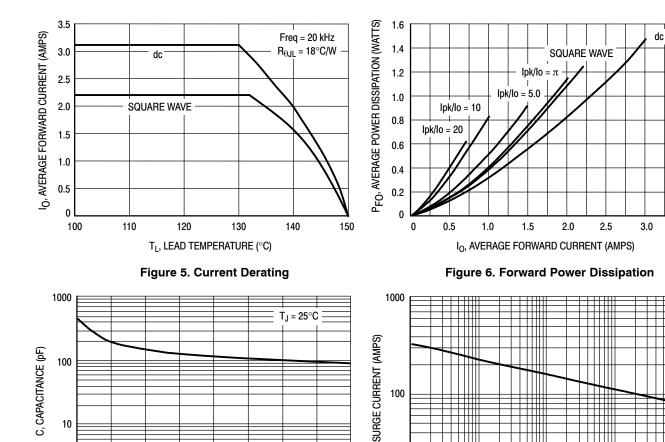


Figure 3. Typical Reverse Current

Figure 4. Maximum Reverse Current

TYPICAL CHARACTERISTICS



V_R, REVERSE VOLTAGE (VOLTS) Figure 7. Capacitance

20

25

30

35

40

Figure 8. Maximum Non-Repetitive **Forward Surge Current**

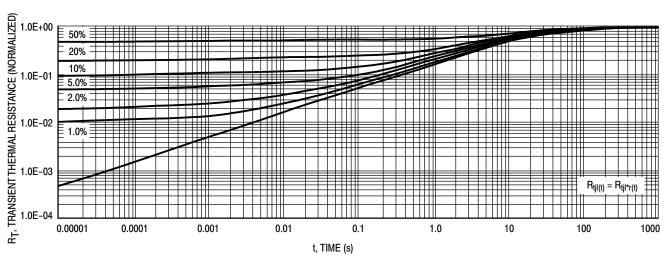
100

PULSE WIDTH (µSEC)

1000

10000

3.5



10

1.0

10

Figure 9. Thermal Response

10

1.0

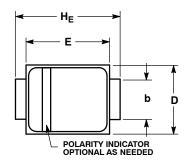
5.0

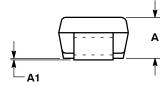
10

15

PACKAGE DIMENSIONS

SMB CASE 403A-03 **ISSUE G**



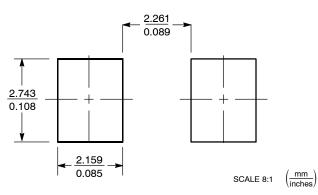


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
 D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.90	2.13	2.45	0.075	0.084	0.096
A1	0.05	0.10	0.20	0.002	0.004	0.008
b	1.96	2.03	2.20	0.077	0.080	0.087
С	0.15	0.23	0.31	0.006	0.009	0.012
D	3.30	3.56	3.95	0.130	0.140	0.156
E	4.06	4.32	4.60	0.160	0.170	0.181
HE	5.21	5.44	5.60	0.205	0.214	0.220
L	0.76	1.02	1.60	0.030	0.040	0.063
L1	0.51 REF			0.020 REF		

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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